

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5012172

SUBMISSION TYPE:	CORRECTIVE ASSIGNMENT
NATURE OF CONVEYANCE:	Corrective Assignment to correct the CORRECT EXECUTED DATES OF 2ND, 3RD AND 4TH INVENTORS previously recorded on Reel 046003 Frame 0186. Assignor(s) hereby confirms the CORRECT EXECUTED DATES OF 2ND, 3RD AND 4TH INVENTORS.

CONVEYING PARTY DATA

Name	Execution Date
MARIO FRANCISCO VELEZ	05/25/2018
NIRANJAN SUNIL MUDAKATTE	05/24/2018
JONGHAE KIM	05/24/2018
CHANGHAN HOBIE YUN	05/24/2018
DAVID FRANCIS BERDY	12/21/2017
SHIQUN GU	11/20/2017
CHENGJIE ZUO	05/05/2018

RECEIVING PARTY DATA

Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15705035

CORRESPONDENCE DATA**Fax Number:**

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Email: qualcomm-pto@lozaip.com

Correspondent Name: LOZA & LOZA LLP

Address Line 1: 305 NORTH SECOND AVENUE #127

Address Line 4: UPLAND, CALIFORNIA 91786

ATTORNEY DOCKET NUMBER:	QCOM-3562US (164357)
NAME OF SUBMITTER:	JULIO LOZA
SIGNATURE:	/Julio Loza/

DATE SIGNED:

06/18/2018

Total Attachments: 17

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PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
MARIO FRANCISCO VELEZ	05/25/2018
NIRANJAN SUNIL MUDAKATTE	11/28/2017
JONGHAE KIM	11/18/2017
CHANGHAN HOBIE YUN	11/15/2017
DAVID FRANCIS BERDY	12/21/2017
SHIQUN GU	11/20/2017
CHENGJIE ZUO	05/05/2018
RECEIVING PARTY DATA	
Name:	QUALCOMM INCORPORATED
Street Address:	5775 MOREHOUSE DRIVE
City:	SAN DIEGO
State/Country:	CALIFORNIA
Postal Code:	92121-1714
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	15705035
CORRESPONDENCE DATA	
Fax Number:	
Email:	qualcomm-pto@lozaip.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	LOZA & LOZA LLP
Address Line 1:	305 NORTH SECOND AVENUE #127
Address Line 4:	UPLAND, CALIFORNIA 91786
ATTORNEY DOCKET NUMBER:	QCOM-3562US (164357)
NAME OF SUBMITTER:	JULIO LOZA

PATENT
REEL: 046379 FRAME: 0495

Signature:	/Julio Loza/
Date:	06/06/2018
Total Attachments: 15 source=164357_ASG_2018_06_01_signed#page1.tif source=164357_ASG_2018_06_01_signed#page2.tif source=164357_ASG_2018_06_01_signed#page3.tif source=164357_ASG_2018_06_01_signed#page4.tif source=164357_ASG_2018_06_01_signed#page5.tif source=164357_ASG_2018_06_01_signed#page6.tif source=164357_ASG_2018_06_01_signed#page7.tif source=164357_ASG_2018_06_01_signed#page8.tif source=164357_ASG_2018_06_01_signed#page9.tif source=164357_ASG_2018_06_01_signed#page10.tif source=164357_ASG_2018_06_01_signed#page11.tif source=164357_ASG_2018_06_01_signed#page12.tif source=164357_ASG_2018_06_01_signed#page13.tif source=164357_ASG_2018_06_01_signed#page14.tif source=164357_ASG_2018_06_01_signed#page15.tif	
RECEIPT INFORMATION	
EPAS ID:	PAT4993890
Receipt Date:	06/06/2018

PATENT
REEL: 046379 FRAME: 0496

06/06/2018, 12:17 PM

ASSIGNMENT

WHEREAS, WE,

1. Mario Francisco VELEZ, a citizen of the United States of America, having a mailing address located at ~~5775 Morehouse Drive, San Diego, CA 92121~~ and a resident of San Diego, California, *13767 Kerry Lane, San Diego, CA, 92130 M.V. 5/25/2018*
2. Niranjan Sunil MUDAKATTE, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
3. Jonghae KIM, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
4. Changan Hobie YUN, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
5. David Francis BERDY, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
6. Shiqun GU, a citizen of the United States of America, having a mailing address located at 5318 Foxhound way, San Diego, CA 92130 and a resident of San Diego, California,
7. Chengjie ZUO, a citizen of the People's Republic of China, having a mailing address located at 16535 Newcomb St., San Diego, CA 92127 and a resident of San Diego, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to INTEGRATED DEVICE COMPRISING A CAPACITOR AND INDUCTOR STRUCTURE COMPRISING A SHARED INTERCONNECT FOR A CAPACITOR AND AN INDUCTOR (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and

transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 15/705,035 filed September 14, 2017, Qualcomm Reference No. 164357, and all provisional applications relating thereto, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at San Diego, CA, on 5/25/2018 
LOCATION DATE Mario Francisco VELEZ

Done at _____, on _____
LOCATION DATE Niranjn Sunil MUDAKATTE

Done at _____, on _____
LOCATION DATE Jonghae KIM

Done at _____, on _____
LOCATION DATE Changhan Hobie YUN

Done at _____, on _____
LOCATION DATE David Francis BERDY

Done at _____, on _____
LOCATION DATE Shiqun GU

Done at _____, on _____
LOCATION DATE Chengjie ZUO

ASSIGNMENT

WHEREAS, WE,

1. Mario Francisco VELEZ, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
2. Niranjan Sunil MUDAKATTE, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
3. Jonghae KIM, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
4. Changhan Hobie YUN, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
5. David Francis BERDY, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
6. Shiqun GU, a citizen of the United States of America, having a mailing address located at 5318 Foxhound way, San Diego, CA 92130 and a resident of San Diego, California,
7. Chengjie ZUO, a citizen of the People's Republic of China, having a mailing address located at 16535 Newcomb St., San Diego, CA 92127 and a resident of San Diego, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to INTEGRATED DEVICE COMPRISING A CAPACITOR AND INDUCTOR STRUCTURE COMPRISING A SHARED INTERCONNECT FOR A CAPACITOR AND AN INDUCTOR (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and

transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 15/705,035 filed September 14, 2017, Qualcomm Reference No. 164357, and all provisional applications relating thereto, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

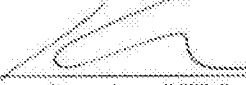
AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE
Mario Francisco VELEZ

Done at SAN DIEGO, on 05/24/2018
LOCATION DATE

Niranjan Sunil MUDAKATTE

Done at San Diego, on 05/24/2018
LOCATION DATE

Jonghae KIM

Done at San Diego, on 5/24/18
LOCATION DATE

Changhan Hobie YUN

Done at _____, on _____
LOCATION DATE
David Francis BERDY

Done at _____, on _____
LOCATION DATE
Shiqun GU

Done at _____, on _____
LOCATION DATE
Chengjie ZUO

ASSIGNMENT

WHEREAS, WE,

1. Mario Francisco VELEZ, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
2. Niranjana Sunil MUDAKATTE, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
3. Jonghae KIM, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
4. Changhan Hobie YUN, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
5. David Francis BERDY, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
6. Shiqun GU, a citizen of the United States of America, having a mailing address located at 5318 Foxhound way, San Diego, CA 92130 and a resident of San Diego, California,
7. Chengjie ZUO, a citizen of the People's Republic of China, having a mailing address located at 16535 Newcomb St., San Diego, CA 92127 and a resident of San Diego, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to INTEGRATED DEVICE COMPRISING A CAPACITOR AND INDUCTOR STRUCTURE COMPRISING A SHARED INTERCONNECT FOR A CAPACITOR AND AN INDUCTOR (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and

transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 15/705,035 filed September 14, 2017, Qualcomm Reference No. 164357, and all provisional applications relating thereto, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;


AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Mario Francisco VELEZ

Done at _____, on _____
LOCATION DATE Niranjan Sunil MUDAKATTE

Done at _____, on _____
LOCATION DATE Jonghae KIM

Done at _____, on _____
LOCATION DATE Chaghan Hobie YUN

Done at San Diego, CA, on 12/21/17
LOCATION DATE 
David Francis BERDY

Done at _____, on _____
LOCATION DATE Shiqun GU

Done at _____, on _____
LOCATION DATE Chengjie ZUO

ASSIGNMENT

WHEREAS, WE,

1. Mario Francisco VELEZ, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
2. Niranjan Sunil MUDAKATTE, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
3. Jonghae KIM, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
4. Changan Hobie YUN, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
5. David Francis BERDY, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
6. Shiqun GU, a citizen of the United States of America, having a mailing address located at 5318 Foxhound way, San Diego, CA 92130 and a resident of San Diego, California,
7. Chengjie ZUO, a citizen of the People's Republic of China, having a mailing address located at 16535 Newcomb St., San Diego, CA 92127 and a resident of San Diego, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to INTEGRATED DEVICE COMPRISING A CAPACITOR AND INDUCTOR STRUCTURE COMPRISING A SHARED INTERCONNECT FOR A CAPACITOR AND AN INDUCTOR (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and

transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 15/705,035 filed September 14, 2017, Qualcomm Reference No. 164357, and all provisional applications relating thereto, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

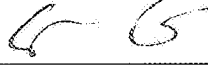
Done at _____, on _____
LOCATION DATE Mario Francisco VELEZ

Done at _____, on _____
LOCATION DATE Niranjan Sunil MUDAKATTE

Done at _____, on _____
LOCATION DATE Jonghae KIM

Done at _____, on _____
LOCATION DATE Changhan Hobie YUN

Done at _____, on _____
LOCATION DATE David Francis BERDY

Done at San Diego, on 11/20/2017
LOCATION DATE 
Shiqun GU

Done at _____, on _____
LOCATION DATE Chengjie ZUO

ASSIGNMENT

WHEREAS, WE,

1. Mario Francisco VELEZ, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
2. Niranjana Sunil MUDAKATTE, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
3. Jonghae KIM, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
4. Changhan Hobie YUN, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
5. David Francis BERDY, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA 92121 and a resident of San Diego, California,
6. Shiqun GU, a citizen of the United States of America, having a mailing address located at 5318 Foxhound way, San Diego, CA 92130 and a resident of San Diego, California,
7. Chengjie ZUO, a citizen of the People's Republic of China, having a mailing address located at 16535 Newcomb St., San Diego, CA 92127 and a resident of San Diego, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to INTEGRATED DEVICE COMPRISING A CAPACITOR AND INDUCTOR STRUCTURE COMPRISING A SHARED INTERCONNECT FOR A CAPACITOR AND AN INDUCTOR (collectively the "INVENTIONS") for which WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, QUALCOMM Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, WE do hereby acknowledge that WE have sold, assigned, conveyed, and

transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not limited to U.S. Application No. 15/705,035 filed September 14, 2017, Qualcomm Reference No. 164357, and all provisional applications relating thereto, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND WE further do acknowledge and agree that WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which WE may be entitled, or that WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND WE HEREBY covenant and agree that WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND WE HEREBY covenant that WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at _____, on _____
LOCATION DATE Mario Francisco VELEZ

Done at _____, on _____
LOCATION DATE Niranjn Sunil MUDAKATTE

Done at _____, on _____
LOCATION DATE Jonghae KIM

Done at _____, on _____
LOCATION DATE Changhan Hobie YUN

Done at _____, on _____
LOCATION DATE David Francis BERDY

Done at _____, on _____
LOCATION DATE Shiqun GU

Done at San Diego, on 5/5/18
LOCATION DATE Chengjie ZUO